

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **19-February-2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015

► **Products affected:**

See attached for affected parts.

► **Detailed Change Information:**

Subject: Transfer of wafer backend of line processing and wafer test from Infineon Newport, Wales to Infineon Kulim, Malaysia

Reason: As part of a manufacturing consolidation plan announced in March 2015, Infineon indicated that it would be closing the Newport, Wales facility and transferring the production capability.

Description: Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015

Wafer Backend Processing

	OLD	NEW
Site	Infineon Technologies Newport Limited	Infineon Technologies AG, Kulim, Malaysia

► **Product Identification:**

Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► **Impact of Change:**

No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of material and the location for assembly and final test will not change.

► **Attachments:**

1079-DISTI42-C4002348-AffectedParts.xlsx

► **Time Schedule:**

- Final qualification report:
- First samples available:
- Intended start of delivery:

Available

On request

03-March-2017

If you have any questions, please do not hesitate to contact your local Sales office.

Sales Name	SP number	OPN	Package
IR3550MTRPBF	SP001531294	IR3550MTRPBF	PQFN 6X6 32L
IR3847MTRPBF	SP001529072	IR3847MTRPBF	PQFN 5X6 29L
IR3447MTRPBF	SP001529928	IR3447MTRPBF	PQFN-29L (5X6)
IRFH8303TRPBF	SP001554820	IRFH8303TRPBF	PQFN 5X6 8L
IRFH7084TRPBF	SP001551936	IRFH7084TRPBF	PQFN 5X6 8L
IRFH4251DTRPBF	SP001556236	IRFH4251DTRPBF	PQFN 5X6 8L
IRFH4253DTRPBF	SP001556246	IRFH4253DTRPBF	PQFN 5X6 8L
IR3448MTRPBF	SP001525916	IR3448MTRPBF	PQFN-29L (5X6)
IR3575MTRPBF	SP001527884	IR3575MTRPBF	PQFN 6X6 30L
IRFH7085TRPBF	SP001560390	IRFH7085TRPBF	PQFN 5X6 8L
IR3846MTRPBF	SP001528688	IR3846MTRPBF	MLPQ 5X7 34L
IR3555MTRPBF	SP001528768	IR3555MTRPBF	PQFN 6X6 30L
IRF60DM206	SP001561876	IRF60DM206	DIRECTFET
IR38062MTRPBF	SP001527818	IR38062MTRPBF	PQFN 5X7 34L